Serial No.: 10/678,830 Examiner: Lee D. Wilson
File Date: October 3, 2003 Art Unit: 3723

LISTING OF CLAIMS

1-11 (Canceled)

12 (Currently Amended) A chemical mechanical polishing pad comprising an interior segment and an outer surface wherein the outer surface is at least 0.05 microns thick and wherein the outer surface comprises a ~~metal~~ film.

13. (Canceled)

14. (Canceled)

15. (Canceled)

16. (Canceled)

17. (New) A chemical mechanical polishing pad of claim 12 wherein the film comprises a material selected from the group consisting of Teflon and metals.

18. (New) A chemical mechanical polishing pad of claim 12 wherein the physical properties of the outer surface are different from the physical properties of the interior segment.

19. (New) A chemical mechanical polishing pad comprising an interior segment and an outer surface wherein the outer surface is at least 0.05 microns thick and wherein the outer surface comprises a material whose physical properties have been modified by subjecting the material of the outer surface to radiation.

20. (New) A chemical mechanical polishing pad of claim 19 wherein the radiation is selected from electron beam radiation, ultraviolet radiation and infrared radiation.

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21. (New) A chemical mechanical polishing pad of claim 19 wherein the radiation is selected from electron beam radiation and infrared radiation.

22. (New) A method for forming a chemical mechanical polishing pad comprising an interior segment and an outer surface, said method comprising:

(a) providing the interior segment of the chemical mechanical polishing pad;

(b) coating the interior segment of the chemical mechanical polishing pad with a film with a material selected from the group consisting of Teflon and metals to form the outer surface of the chemical mechanical polishing pad;

wherein the outer surface is at least 0.05 microns thick.

23. (New) A method according to claim 22 wherein the coating occurs by at least one method selected from the group consisting of dip, spray, spin-coating, vacuum metallization, sputtering and electroless plating.

24. (New) A method of forming a chemical mechanical polishing pad comprising an interior segment and an outer surface, said method comprising:

(a) providing the interior segment of the chemical mechanical polishing pad;

(b) forming the outer surface of the chemical mechanical polishing pad using a portion of the interior segment, by contacting said portion of the interior segment with radiation such that the physical properties of the outer surface are changed in relation to the physical properties of the remainder of the interior segment as a result of the contact with radiation;

wherein the outer surface is at least 0.05 microns thick.

25. (New) A method according to claim 24 wherein the radiation is selected from the group consisting of electron beam radiation, ultra violet radiation and infrared radiation.

26. (New) A method according to claim 24 wherein the radiation is selected from the group consisting of electron beam radiation and infrared radiation.